

CBR08C229B1GAC

CBR-SMD RF COG, Ceramic, 2.2 pF, +/-0.1 pF, 100 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0805 / 2012



Click [here](#) for the 3D model.

General Information

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|--------------------------|--|
| Series | CBR-SMD RF COG |
| Style | SMD Chip |
| Description | SMD, Fixed, RF, Ultra High Q, Low ESR, Class I |
| Features | Ultra High Q, Low ESR, Class I |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| Typical Component Weight | 12.03 mg |
| Notes | Solder Wave or Solder Reflow. |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Dimensions

| | |
|----------------------|-----------------|
| L | 2mm +/-0.2mm |
| W | 1.25mm +/-0.2mm |
| T | 0.85mm +/-0.1mm |
| B | 0.5mm +/-0.2mm |
| Case Code (EIA / mm) | 0805 / 2012 |

Packaging Specifications

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|--------------------|--------------------------|
| Packaging | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 4000 |

Specifications

| | |
|---------------------------------|---------------------|
| Capacitance | 2.2 pF |
| Tolerance | +/-0.1 pF |
| Voltage DC | 100 VDC |
| Dielectric Withstanding Voltage | 250 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | COG |
| Dissipation Factor | 0.225% |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 10 GOhms |
| Quality Factor | 444 |

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